

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Number: 10/601,464
Application Filed: June 23, 2003
Applicant: Miller, Ronald Brooks
Title: MULTI-LAYER CIRCUIT BOARD AND METHOD
OF MANUFACTURE
Examiner: Patel, Ishwarbhai
Art Unit: 2841
To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**REMARKS IN RESPONSE TO
FINAL OFFICE ACTION**

I. Introduction

The following remarks are respectfully submitted in response to the Final Office Action in this matter. In view of the following Amendments and Remarks, the Examiner is respectfully requested to consider the amended claims, and reconsider and withdraw the outstanding rejections and objections and allow all claims pending in the application. Applicant is concurrently filing a Request for Continued Examination.

II. Amended Title

Applicant originally titled this invention "Method for Embedding an Air Dielectric Transmission Line in a Printed Wiring Board (PCB)". The Examiner has argued that the claims